

CIR-V4SESW2416G

DDR4 SO-DIMM 2400MHz 16GB with ECC

Description

This specification defines the electrical and mechanical requirements for 260 pin, 1.2 V (VDD), Double Data Rate, Synchronous DRAM Dual In-Line Memory Modules (DDR4 SDRAM ECC SO-DIMM). This DDR4 ECC SO-DIMMs is intended for use as main memory when installed in PCs, laptops and other systems.

Reference design examples are included which provide an initial basis for DDR4 ECC SO-DIMM designs. Modifications to these reference designs may be required to meet all system timing, signal integrity and thermal requirements for DDR4-2400 support.

All DDR4 ECC SO-DIMM implementations must use simulations and lab verification to ensure proper timing requirement and signal integrity in the design.

| | Specifications | | | | | |
|---|------------------------|-------------------|--|--|--|--|
| [| Density | 16GB | | | | |
| I | Pin Count | 260pin | | | | |
| - | Туре | Unbuffered | | | | |
| [| Dimensions | 69.73mm x 30.13mm | | | | |
| I | ECC | with ECC | | | | |
| (| Component Config | 1G x 8 bit | | | | |
| [| Data Rate | 2400 MHz | | | | |
| (| CAS Latency | 17 | | | | |
| ` | Voltage | 1.2V | | | | |
| I | PCB Layers | 8 | | | | |
| (| Operating Temp.(TCASE) | 0°C~+85°C | | | | |
| I | Module Ranks | Dual Rank | | | | |
| | | | | | | |

Features

- JEDEC Standard 260-pin Small-Outline Dual In-Line Memory Module
- VDD=VDDQ = 1.2V±0.06V (1.14V~1.26V)
- Programmable CAS Latency(posted CAS): 11,12,13,14,15,16,17
- Inputs and Outputs are SSTL-12 compatible
- Low-Power auto self-refresh (LPASR)
- SDRAMs have 16 internal banks for concurrent operation (4 Bank Group of 4banks each)
- Normal and Dynamic On-Die Termination for data, strobe and mask signals.
- Data bus inversion (DBI) for data bus
- Fixed burst chop (BC) of 4 and burst length (BL) of 8 via the MRS
- Selectable BC4 or BL8 on-the fly (OTF)
- ECC function support
- RoHS and Halogen free

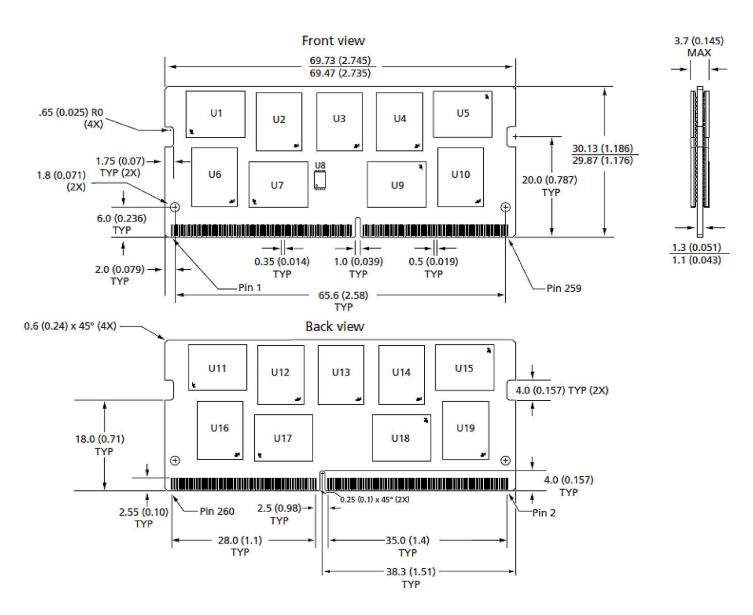


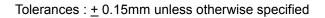
Speed Grade

| Frequency | Data Transfer Rate | CAS Latency Support | | | | | | | |
|-----------|--------------------------|---------------------|------|------|------|------|------|------|-------------|
| Grade | | CL11 | CL12 | CL13 | CL14 | CL15 | CL16 | CL17 | CL-tRCD-tRP |
| DDR4-2400 | PC4-19200 | 1600 | 1600 | 1866 | 1866 | 2133 | 2133 | 2400 | 17-17-17 |

Package Dimensions

Unit: mm





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